



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

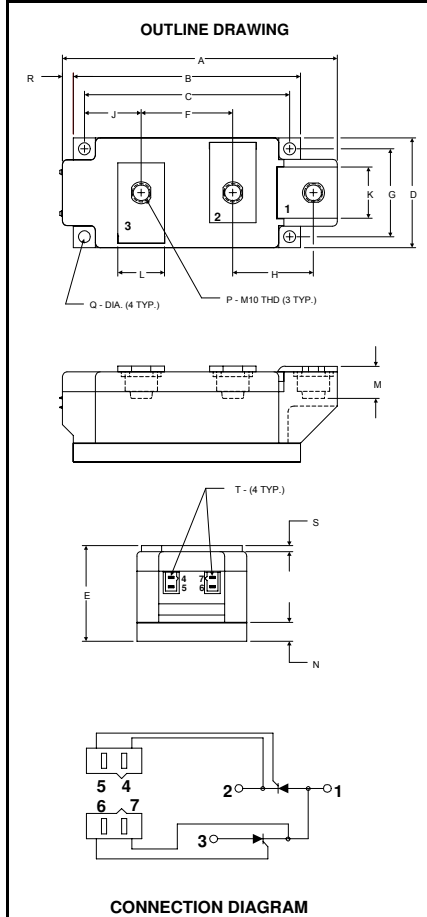
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**POW-R-BLOK™**  
**Dual SCR Isolated Module**  
**500 Amperes / Up to 1600 Volts**



**LD43\_50**  
**Dual SCR**  
**POW-R-BLOK™ Module**  
 500 Amperes / 800-1600 Volts

**LD43 Outline Dimensions**

Dimension	Inches	Millimeters
A	5.91	150.0
B	4.88	124.0
C	4.41	112.0
D	2.36	60.0
E	2.05	52.0
F	1.97	50.0
G	1.89	48.0
H	1.73	44.0
J	1.22	31.0
K	1.10	28.0
L	1.00	25.4
M	0.69	17.5
N	0.39	10.0
P	M10 Metric	M10
Q	0.26 Dia.	6.5 Dia.
R	0.24	6.0
S	0.12	3.0
T	.110 x .032	2.5 x 0.8

Note: Dimensions are for reference only.

**Ordering Information:**

Select the complete eight-digit module part number from the table below.

Example: LD431650 is a 1600V, 500 Ampere Dual SCR Isolated POW-R-BLOK™ Module.

Type	Voltage Volts (x100)	Current Amperes (x10)
LD43	08	50
	10	
	12	
	14	
	16	

**Description:**

Powerex Dual SCR Modules are designed for use in applications requiring phase control and isolated packaging. The modules are isolated for easy mounting with other components on a common heatsink. POW-R-BLOK™ has been tested and recognized by the Underwriters Laboratories.

**Features:**

- Electrically Isolated Heatsinking
- Aluminum Nitride Isolator
- Compression Bonded Elements
- Metal Baseplate
- Low Thermal Impedance for Improved Current Capability
- UL Recognized

**Benefits:**

- No Additional Insulation Components Required
- Easy Installation
- No Clamping Components Required
- Reduce Engineering Time

**Applications:**

- Bridge Circuits
- AC & DC Motor Drives
- Battery Supplies
- Power Supplies
- Large IGBT Circuit Front Ends

**Absolute Maximum Ratings**

Characteristics	Conditions	Symbol	Units
Repetitive Peak Forward and Reverse Blocking Voltage		$V_{DRM}$ & $V_{RRM}$	up to 1600 V
Non-Repetitive Peak Blocking Voltage ( $t < 5$ msec)		$V_{RSM}$	$V_{RRM} + 100$ V
RMS Forward Current		$I_{T(RMS)}$	900 A
Average Forward Current	180° Conduction, $T_C=86^\circ\text{C}$	$I_{T(AV)}$	500 A
Peak One Cycle Surge Current, Non-Repetitive	60 Hz, 100% $V_{RRM}$ reapplied	$I_{TSM}$	17,000 A
	50 Hz, 100% $V_{RRM}$ reapplied	$I_{TSM}$	16,300 A
Peak Three Cycle Surge Current, Non-Repetitive	60 Hz, 100% $V_{RRM}$ reapplied	$I_{TSM}$	12,250 A
Peak Ten Cycle Surge Current, Non-Repetitive	60 Hz, 100% $V_{RRM}$ reapplied	$I_{TSM}$	10,500 A
$I^2t$ for Fusing for One Cycle	8.3 milliseconds	$I^2t$	$1.20 \times 10^6$ A <sup>2</sup> sec
	10 milliseconds	$I^2t$	$1.33 \times 10^6$ A <sup>2</sup> sec
Maximum Rate-of-Rise of On-State Current, (Repetitive)	Per JEDEC Standard 397 5.2.2.6	di/dt	200 A/ $\mu$ s
Operating Temperature		$T_J$	-40 to +130 °C
Storage Temperature		$T_{stg}$	-40 to +150 °C
Max. Mounting Torque, M6 Mounting Screw			55 in. – Lb.
			6 Nm
Max. Mounting Torque, M10 Terminal Screw			110 in. – Lb.
			12 Nm
Module Weight, Typical			1500 g
			3.30 lb
V Isolation @ 25C		$V_{rms}$	3000 V

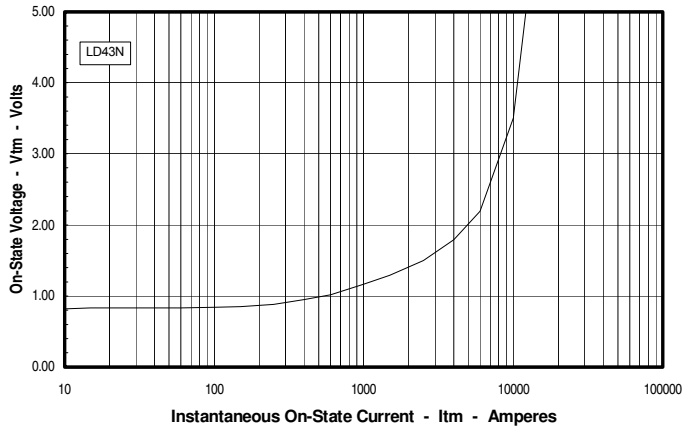
**Electrical Characteristics, T<sub>J</sub>=25°C unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Max.	Units
Repetitive Peak Forward Leakage Current	I <sub>DRM</sub>	Up to 1600V, T <sub>J</sub> =130°C		80	mA
Repetitive Peak Reverse Leakage Current	I <sub>RRM</sub>	Up to 1600V, T <sub>J</sub> =130°C		80	mA
Peak On-State Voltage	V <sub>FM</sub>	I <sub>TM</sub> =1500A		1.30	V
Threshold Voltage, Low-level	V <sub>(TO)1</sub>	T <sub>J</sub> = 130°C, I = 15%I <sub>T(AV)</sub> to πI <sub>T(AV)</sub>		0.81	V
Slope Resistance, Low-level	r <sub>T1</sub>			0.32	mΩ
Threshold Voltage, High-level	V <sub>(TO)2</sub>	T <sub>J</sub> = 130°C, I = πI <sub>T(AV)</sub> to I <sub>TSM</sub>		0.90	V
Slope Resistance, High-level	r <sub>T2</sub>			0.26	mΩ
V <sub>TM</sub> Coefficients, Full Range		T <sub>J</sub> = 130°C, I = 10A to 6kA V <sub>TM</sub> = A + B Ln I + C I + D Sqrt I	A = B = C = D =	0.8824 -4.46E-02 8.12E-05 1.54E-02	
Minimum dV/dt	dV/dt	Exponential to V <sub>DRM</sub> T <sub>J</sub> =130°C, Gate Open	1000 Typ.		V/μs
Gate Trigger Current	I <sub>GT</sub>	T <sub>J</sub> =25°C, V <sub>D</sub> =12V		200	mA
Gate Trigger Voltage	V <sub>GT</sub>	T <sub>J</sub> =25°C, V <sub>D</sub> =12V		3.0	Volts
Non-Triggering Gate Voltage	V <sub>GDM</sub>	T <sub>J</sub> =130°C, V <sub>D</sub> = ½ V <sub>DRM</sub>		0.25	Volts
Peak Forward Gate Current	I <sub>GTM</sub>			4.0	Amp
Peak Reverse Gate Voltage	V <sub>GRM</sub>			5	Volts

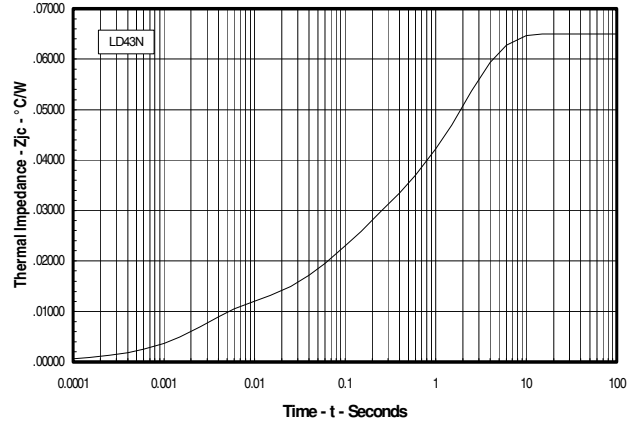
**Thermal Characteristics**

Characteristics	Symbol		Max.	Units
Thermal Resistance, Junction to Case	R <sub>θJ-C</sub>	Per Module, both conducting Per Junction, both conducting	0.0325 0.0650	°C/W °C/W
Thermal Impedance Coefficients	Z <sub>θJ-C</sub>	Z <sub>θJ-C</sub> = K <sub>1</sub> (1-exp(-t/τ <sub>1</sub> )) + K <sub>2</sub> (1-exp(-t/τ <sub>2</sub> )) + K <sub>3</sub> (1-exp(-t/τ <sub>3</sub> )) + K <sub>4</sub> (1-exp(-t/τ <sub>4</sub> ))	K <sub>1</sub> = 8.03E-04 K <sub>2</sub> = 1.03E-02 K <sub>3</sub> = 1.64E-02 K <sub>4</sub> = 3.75E-02	τ <sub>1</sub> = 3.39E-04 τ <sub>2</sub> = 3.15E-03 τ <sub>3</sub> = 0.106 τ <sub>4</sub> = 2.066
Thermal Resistance, Case to Sink Lubricated	R <sub>θC-S</sub>	Per Module	0.01	°C/W

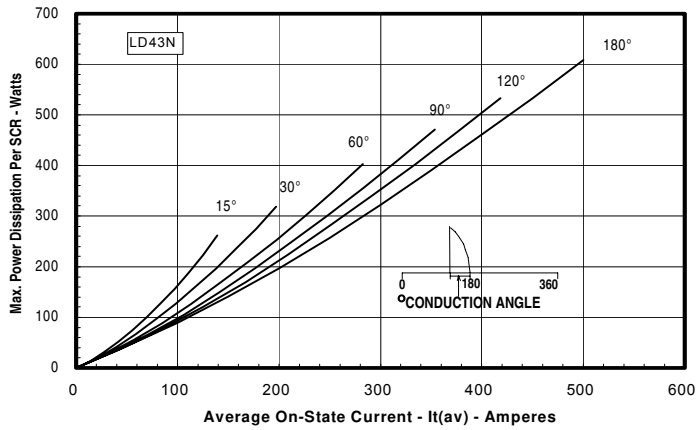
**Maximum On-State Forward Voltage Drop**  
 (T<sub>j</sub> = 130 °C)



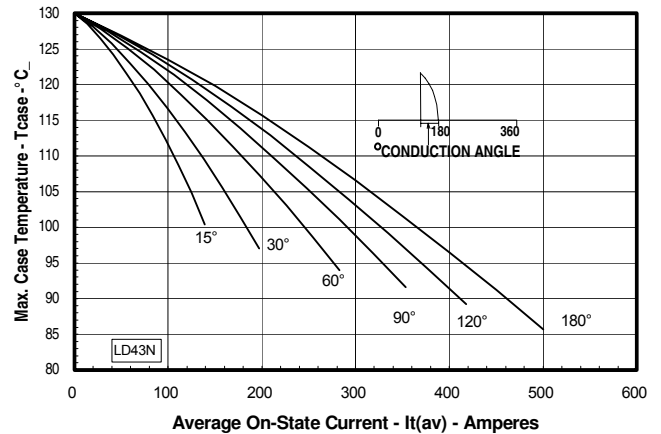
**Maximum Transient Thermal Impedance**  
 (Junction to Case)



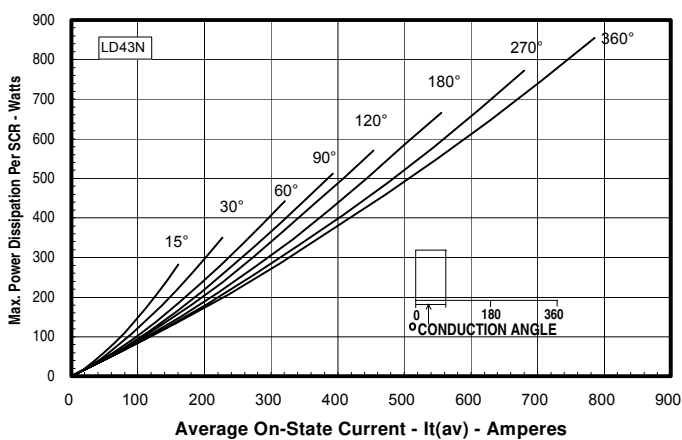
**Maximum On-State Power Dissipation**  
 (Sinusoidal Waveform)



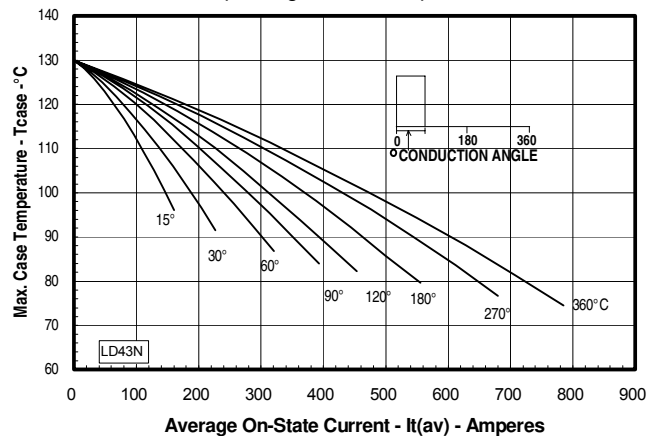
**Maximum Allowable Case Temperature**  
 (Sinusoidal Waveform)



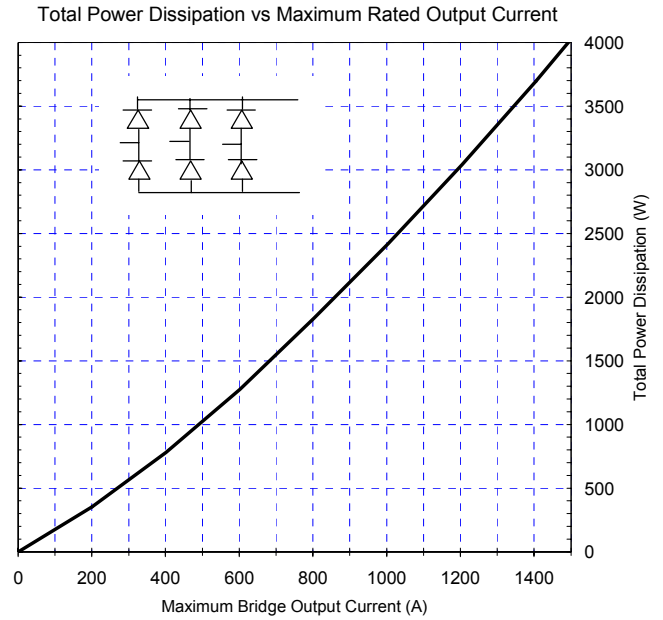
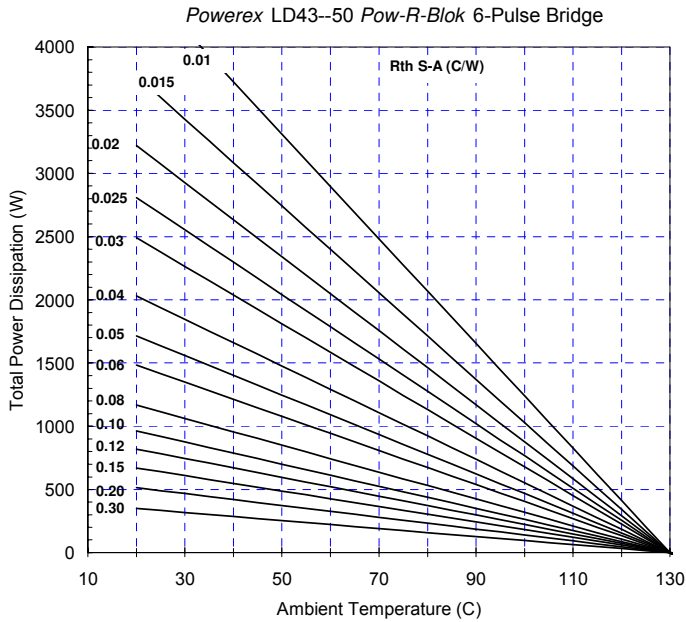
**Maximum On-State Power Dissipation**  
 (Rectangular Waveform)



**Maximum Allowable Case Temperature**  
 (Rectangular Waveform)







Six-Pulse Bridge Circuit Total Power Dissipation & Maximum Rated Output Current With Sink to Ambient Resistance of Heatsink as a Parameter.